

IN THE SPECIFICATION

Please replace the paragraph beginning on page 40, line 26 to page 41, line 5 with the following amended paragraph:

In the ~~first~~ second embodiment, the deformation amount of the elastic member 104 by the positioning is detected by the strain gauge 108. The deformation amount of the elastic member 104 is a difference of a positional relation between the lower substrate 112 and the lower stage 132 shown in FIG. 10 from that between the lower substrate 112 and the lower stage 132 shown in FIG. 11.

Please replace the paragraph beginning on page 59, line 20 to page 60, line 2 with the following amended paragraph:

According to the apparatus for bonding the substrates and the method of bonding the substrates according to the present invention described above, the elastic member for uniform and high-quality ~~elastic member~~ bonding is deformed in the positioning operation, but the bonding precision can be prevented from being deteriorated by the restoring force. With the use of the apparatus and method in steps of manufacturing liquid crystal substrates or the like, superior effects can be obtained.